

# PRODUCT SPECIFICATION

## MONO LCD MODULE MODEL: G2406B1SGW1G-A0 Ver:1.0

< ◇ > Preliminary Specification

< ◆ > Finally Specification

CUSTOMER'S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED By



## Table of Contents

No.	Contents	Page
1.	FEATURES.....	4
2.	MECHANICAL SPECIFICATIONS.....	4
3.	ELECTRICAL SPECIFICATIONS.....	4
4.	TERMINAL FUNCTIONS AND BLOCK DIAGRAM.....	6
5.	TIMING CHARACTERISTICS.....	8
6.	COMMAND LIST.....	11
7.	CHARACTER GENERATOR ROM.....	12
8.	QUALITY SPECIFICATIONS.....	17
9.	RELIABILITY.....	18
11.	OUTLINE DIMENSION.....	19

## 1. Features

The features of LCD are as follows

- \* Display mode : STN/Blue/Transmissive/ Negative
- \* IC : UC1608
- \* Interface Input Data :6800-4bit/8bit,8080-4bit/8bit,3-wire SPI w/9-bit,4-wire-SPI w/8-bit,3/4wire SPI w/8-bit
- \* Driving Method : 1/64 Duty, 1/9 Bias
- \* Viewing Direction : 6 O'clock
- \* Backlight : LED /WHITE
- \*Sample NO : G2406B1SGW1G-A0\_01/20110127

## 2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	126.2(W) x 55.1(H) x 5.8(T)	mm
Viewing Area	111 (W) x 37 (H)	mm
Activity Area	105.57(W) x 31.97(H)	mm
Number of Dots	240 x 64 Dots	-
Dot Size	0.41(W) x 0.47(H)	mm
Dot Pitch	0.44(W) x 0.5(H)	mm

## 3. ELECTRICAL SPECIFICATIONS

### 3-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Standard Value			Unit
		Min.	Typ.	Max.	
Supply Voltage For Logic	$V_{DD}-V_{SS}$	-0.3	-	4.0	V
Supply Voltage For LCD Drive	$V_{OP}= V_{DD}-V_0$	-0.3	-	17	V
Input Voltage	$V_{in}$	-0.4	-	$V_{DD}+0.5$	V
Operating Temp.	$T_{op}$	-10	-	+60	°C
Storage Temp.	$T_{st}$	-20	-	+70	°C

\*. NOTE: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

**3-2 ELECTRICAL CHARACTERISTICS**

Item	Symbol	Test Condition	Min.	Typ.	Max.	Unit	
Logic supply Voltage	$V_{DD}-V_{SS}$	$T_a = 25\text{ }^\circ\text{C}$ $V_{DD}=3V \pm 10\%$	2.7	3	3.3	V	
LCD Drive	$V_{OP}=V_{DD}-V_0$		13	13.3	13.6	V	
Input Voltage	"H" Level		$V_{IH}$	-	-	$0.2V_{DD}$	V
	"L" Level		$V_{IL}$	$0.8V_{DD}$	-	-	V
Frame Frequency	$f_{FLM}$		-	75	-	Hz	
Current Consumption	$I_{DD}$		-	0.86	-	mA	

**3-3. BACKLIGHT****3-3-1. Absolute Maximum Ratings**

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Current	IF	$T_a = 25\text{ }^\circ\text{C}$	-	-	90	mA
Reverse Voltage	VR		-	-	5	V
Power Dissipation	PD		-	-	720	mW

**3-3-2. Electrical-optical Characteristics**

Item	Symbol	Condition	Min.		Typ.		Max.		Unit
Forward Voltage	VF	$T_a = 25\text{ }^\circ\text{C}$ $I_f=90\text{mA}$	2.9		3.1		3.3		V
Average Luminous Intensity	$I_v$		250		-		-		$\text{cd/m}^2$
Colour coordinates	-		X	Y	X	Y	X	Y	-
			0.27	0.27	-	-	0.33	0.33	

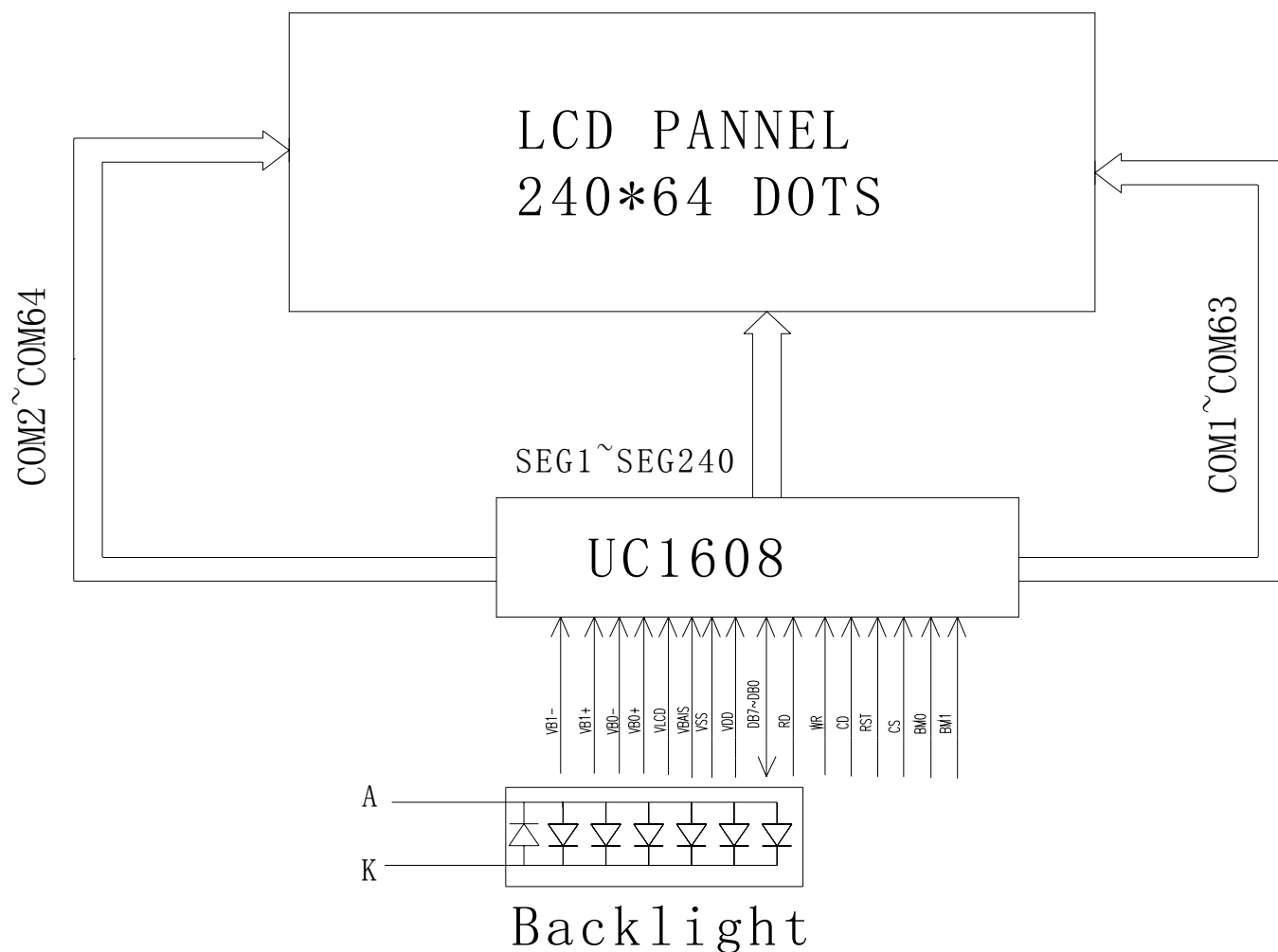
The brightness is measured without LCD panel

## 4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

### 4-1. INTERFACE PIN FUNCTION DESCRIPTION

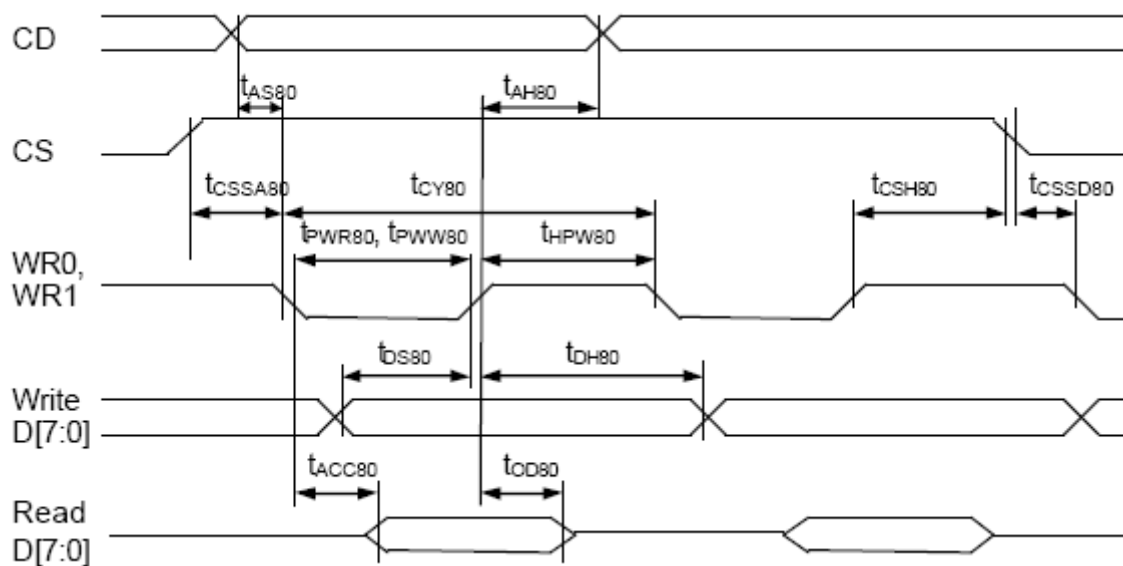
Pin No.	Pin Name	Function																								
1	NC	Not connect pin																								
2~5	VB1-,VB1+,VB0-,VB0+	LCD bias voltage																								
6	VLCD	LCD Power Supply																								
7	VBIAS	This is the reference voltage to generate the actual seg driving voltage																								
8	VSS	Ground																								
9	VDD	VDD is digital VDD																								
10~17	DB7~DB0	Command/data selectionData bus																								
18	RD	Read operation																								
19	WR	Write operation																								
20	CD	Control data/dataselction																								
21	RST	Reset signal																								
22	CS	Chip selection																								
23~24	BM0,BM1	<p>Bus mode: The interface bus mode is determined by BM[1:0] and D[7:6] by the following relationship:</p> <table border="1"> <thead> <tr> <th>BM[1:0]</th> <th>D[7:6]</th> <th>Mode</th> </tr> </thead> <tbody> <tr> <td>11</td> <td>Data</td> <td>6800/8-bit</td> </tr> <tr> <td>10</td> <td>Data</td> <td>8080/8-bit</td> </tr> <tr> <td>01</td> <td>0X</td> <td>6800/4-bit</td> </tr> <tr> <td>00</td> <td>0X</td> <td>8080/4-bit</td> </tr> <tr> <td>01</td> <td>10</td> <td>3-wire SPI w/ 9-bit token (S9: conventional)</td> </tr> <tr> <td>00</td> <td>10</td> <td>4-wire SPI w/ 8-bit token (S8: conventional)</td> </tr> <tr> <td>00</td> <td>11</td> <td>3/4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)</td> </tr> </tbody> </table>	BM[1:0]	D[7:6]	Mode	11	Data	6800/8-bit	10	Data	8080/8-bit	01	0X	6800/4-bit	00	0X	8080/4-bit	01	10	3-wire SPI w/ 9-bit token (S9: conventional)	00	10	4-wire SPI w/ 8-bit token (S8: conventional)	00	11	3/4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)
BM[1:0]	D[7:6]	Mode																								
11	Data	6800/8-bit																								
10	Data	8080/8-bit																								
01	0X	6800/4-bit																								
00	0X	8080/4-bit																								
01	10	3-wire SPI w/ 9-bit token (S9: conventional)																								
00	10	4-wire SPI w/ 8-bit token (S8: conventional)																								
00	11	3/4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)																								

4-2. BLOCK DIAGRAM



## 5. TIMING CHARACTERISTICS

Parallel Bus Timing Characteristics (for 8080 MCU)

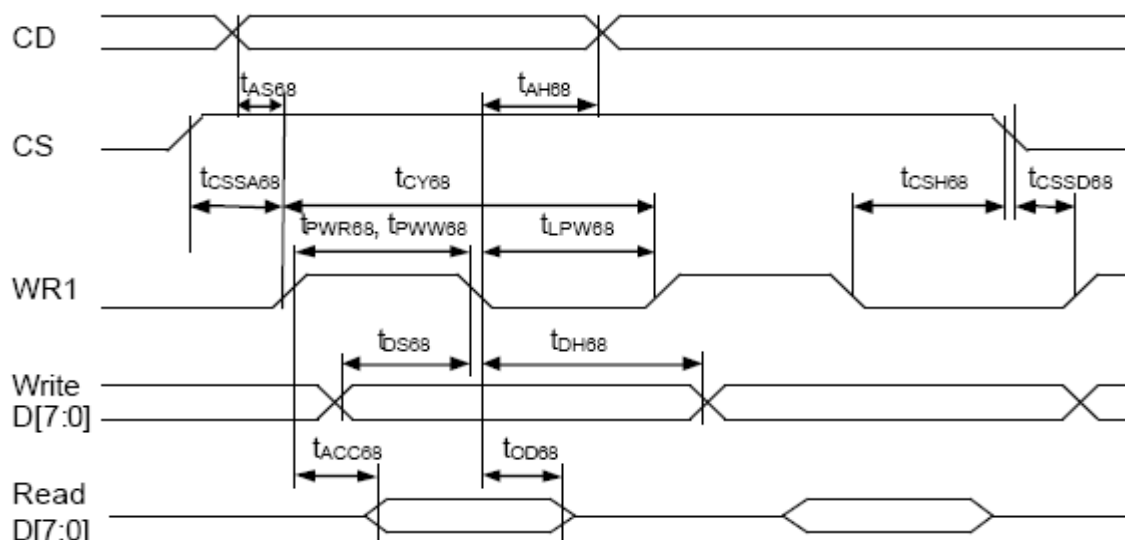


( $2.7V \leq V_{DD} < 3.3V$ ,  $T_a = -30$  to  $+85^\circ C$ )

Symbol	Signal	Description	Condition	Min.	Max.	Units
$t_{AS80}$	CD	Address setup time		0	-	nS
$t_{AH80}$		Address hold time		20	-	nS
$t_{CY80}$		System cycle time				nS
		8 bits bus (read)		140		
		(write)		140		
		4 bits bus (read)		140		
		(write)		140		
$t_{PWR80}$	WR1	Pulse width 8 bits (read)		65	-	nS
		4 bits		65		
$t_{PWW80}$	WR0	Pulse width 8 bits (write)		35	-	nS
		4 bits		35		
$t_{HPW80}$	WR0, WR1	High pulse width				nS
		8 bits bus (read)		65		
		(write)		35		
		4 bits bus (read)		65		
		(write)		35		
$t_{DS80}$	D0~D7	Data setup time		30	-	nS
$t_{DH80}$		Data hold time		20		
$t_{ACC80}$		Read access time	$C_L = 100pF$	-	60	nS
$t_{OD80}$		Output disable time		12	20	nS
$t_{SSA80}$	CS1/CS0	Chip select setup time		10		nS
$t_{CSSD80}$				10		
$t_{CSH80}$				20		



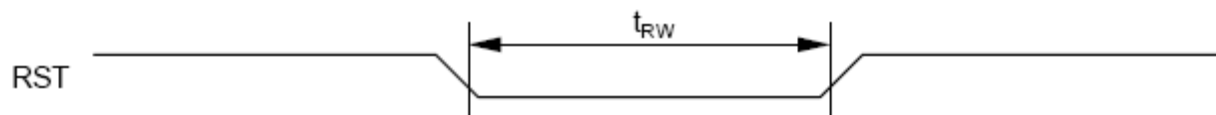
Parallel Bus Timing Characteristics (for 6800 MCU)



( $2.7V \leq V_{DD} < 3.3V$ ,  $T_a = -30$  to  $+85^\circ C$ )

Symbol	Signal	Description	Condition	Min.	Max.	Units
$t_{AS68}$	CD	Address setup time		0	-	nS
$t_{AH68}$	CD	Address hold time		20	-	nS
$T_{CY68}$		System cycle time				nS
		8 bits bus (read)		140		
		(write)		140		
		4 bits bus (read)		140		
		(write)		140		
$t_{PWR68}$	WR1	Pulse width 8 bits (read)		65		
		4 bits		65	-	nS
$t_{PWW68}$		Pulse width 8 bits (write)		35	-	nS
		4 bits		35	-	nS
$t_{LPW68}$		Low pulse width				nS
		8 bits bus (read)		65		
		(write)		35		
		4 bits bus (read)		65		
		(write)		35		
$t_{DS68}$	D0~D7	Data setup time		30	-	nS
$t_{DH68}$	D0~D7	Data hold time		20	-	nS
$t_{ACC68}$		Read access time	$C_L = 100pF$	-	60	nS
$t_{OD68}$		Output disable time		12	20	nS
$t_{CSSA68}$	CS1/CS0	Chip select setup time		10		nS
$t_{CSSD68}$	CS1/CS0	Chip select setup time		10		nS
$t_{CSH68}$	CS1/CS0	Chip select setup time		20		nS

Reset timing



( $2.7V \leq V_{DD} < 3.3V$ ,  $T_a = -30$  to  $+85^\circ C$ )

Symbol	Signal	Description	Condition	Min.	Max.	Units
$t_{RW}$	RST	Reset low pulse width		1000	-	nS

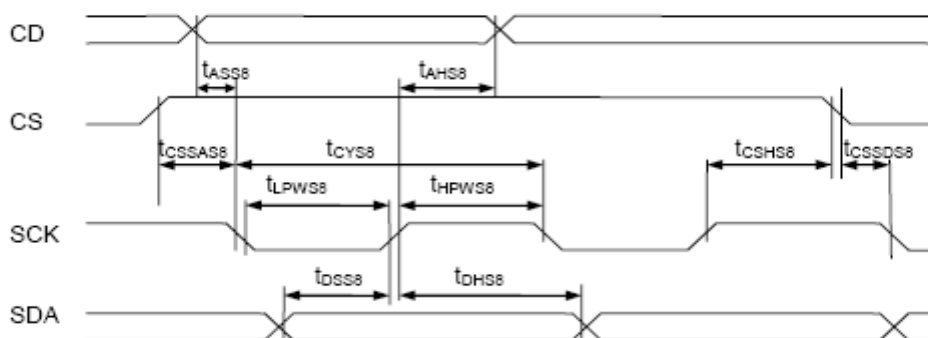


FIGURE 17: Serial Bus Timing Characteristics (for S8)

( $2.7V \leq V_{DD} < 3.3V$ ,  $T_a = -30$  to  $+85^\circ C$ )

Symbol	Signal	Description	Condition	Min.	Max.	Units
tASS8	CD	Address setup time		0	-	nS
tAHS8		Address hold time		20	-	nS
tCYS8	SCK	System cycle time		140	-	nS
tLPWS8		Low pulse width		65	-	nS
tHPWS8		High pulse width		65	-	nS
tDSS8	SDA	Data setup time		30	-	nS
tDHS8		Data hold time		20	-	nS
tCSSAS8	CS	Chip select setup time		10		nS
tCSSDS8				20		
tCSHS8				10		

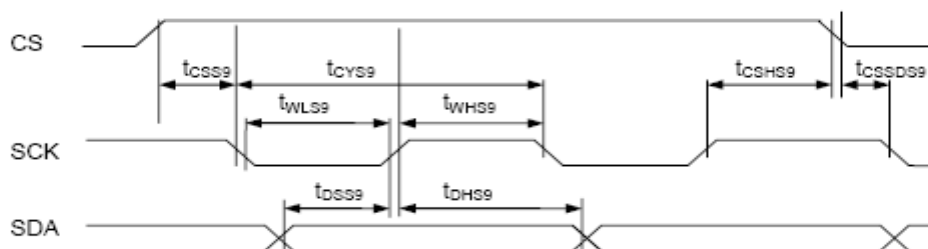


FIGURE 18: Serial Bus Timing Characteristics (for S9)

( $2.7V \leq V_{DD} < 3.3V$ ,  $T_a = -30$  to  $+85^\circ C$ )

Symbol	Signal	Description	Condition	Min.	Max.	Units
tCYS9	SCK	System cycle time		140	-	nS
tLPWS9		Low pulse width		65	-	nS
tHPWS9		High pulse width		65	-	nS
tDSS9	SDA	Data setup time		30	-	nS
tDHS9		Data hold time		20	-	nS
tCSSAS9	CS	Chip select setup time		10		nS
tCSSDS9				20		
tCSHS9				10		

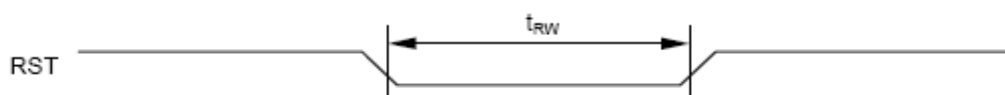


FIGURE 19: Reset Characteristics

( $2.7V \leq V_{DD} < 3.3V$ ,  $T_a = -30$  to  $+85^\circ C$ )

Symbol	Signal	Description	Condition	Min.	Max.	Units
tRW	RST	Reset low pulse width		1000	-	nS

## 6. INSTRUCTION SET

The following is a list of host commands supported by UC1608

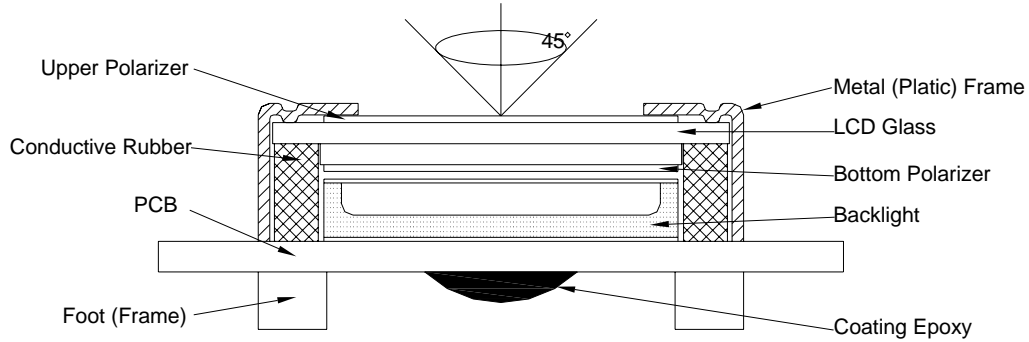
C/D: 0: Control, 1: Data  
 W/R: 0: Write Cycle, 1: Read Cycle  
 # Useful Data bits  
 - Don't Care

	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Default
1	Write Data Byte	1	0	#	#	#	#	#	#	#	#	Write 1 byte	N/A
2	Read Data Byte	1	1	#	#	#	#	#	#	#	#	Read 1 byte	N/A
3	Get Status	0	1	BZ	MX	DE	RS	WA	GN1	GN0	1	Get Status	N/A
4	Set Column Address LSB	0	0	0	0	0	0	#	#	#	#	Set CA[3:0]	0
	Set Column Address MSB	0	0	0	0	0	1	#	#	#	#	Set CA[7:4]	0
5	Set Mux Rate and temperature compensation.	0	0	0	0	1	0	0	#	#	#	Set {MR, TC[1:0]}	MR: 1b TC: 00b
6	Set Power Control	0	0	0	0	1	0	1	#	#	#	Set PC[2:0]	101b
7	Set Adv. Program Control. (double byte command)	0	0	0	0	1	1	0	0	0	R	For UltraChip only. Do not use.	N/A
		0	0	#	#	#	#	#	#	#	#		
8	Set Start Line	0	0	0	1	#	#	#	#	#	#	Set SL[5:0]	0
9	Set Gain and Potentiometer (double-byte command)	0	0	1	0	0	0	0	0	0	1	Set {GN[1:0], PM[5:0]}	GN=3 PM=0
		0	0	#	#	#	#	#	#	#	#		
10	Set RAM Address Control	0	0	1	0	0	0	1	#	#	#	Set AC[2:0]	001b
11	Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]	0=disable
12	Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]	0=disable
13	Set Display Enable	0	0	1	0	1	0	1	1	1	#	Set DC[2]	0=disable
14	Set Fixed Lines	0	0	1	0	0	1	#	#	#	#	Set FL[3:0]	0
15	Set Page Address	0	0	1	0	1	1	#	#	#	#	Set PA[3:0]	0
16	Set LCD Mapping Control	0	0	1	1	0	0	#	#	#	#	Set LC[3:0]	0
17	System Reset	0	0	1	1	1	0	0	0	1	0	System Reset	N/A
18	NOP	0	0	1	1	1	0	0	0	1	1	No operation	N/A
19	Set LCD Bias Ratio	0	0	1	1	1	0	1	0	#	#	Set BR[1:0]	10b=12
20	Reset Cursor Mode	0	0	1	1	1	0	1	1	1	0	AC[3]=0, CA=CR	N/A
21	Set Cursor Mode	0	0	1	1	1	0	1	1	1	1	AC[3]=1, CR=CA	N/A
22	Set Test Control (double byte command)	0	0	1	1	1	0	0	1	TT		For UltraChip only. Do not use.	N/A
		0	0	#	#	#	#	#	#	#	#		

## 7. QUALITY SPECIFICATIONS

### 7 - 1. LCM Appearance and Electric inspection Condition

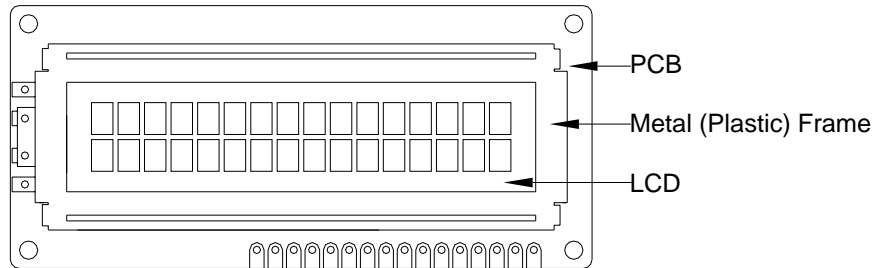
1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



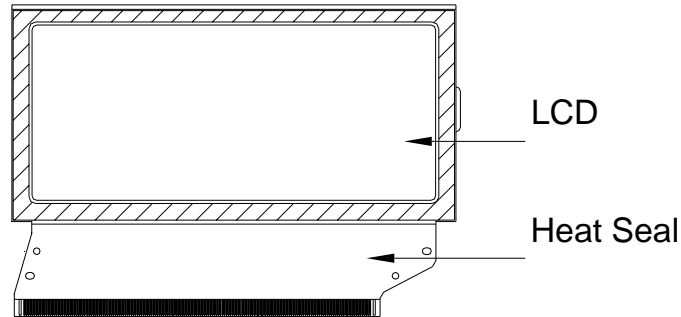
2. View Angle: with in 45° around perpendicular line.

### 7 - 2. Definition

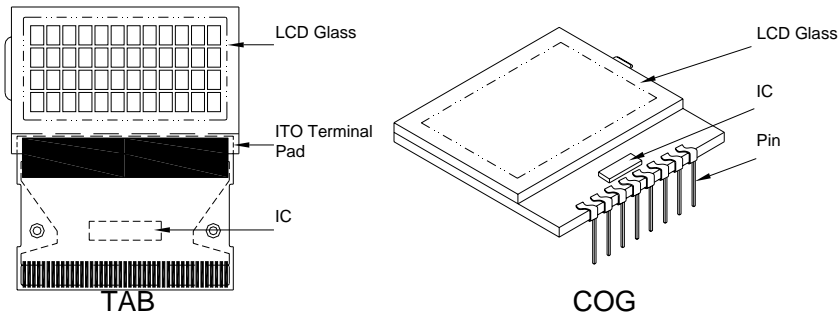
#### 1. COB



#### 2. Heat Seal



#### 3. TAB and COG



**7-3. Sampling Plan and Acceptance**

## 1. Sampling Plan

MIL - STD - 105E ( || ) ordinary single inspection is used.

## 2. Acceptance

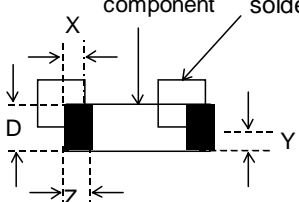
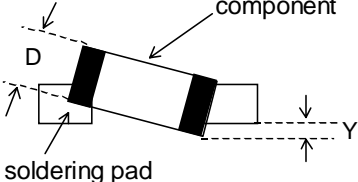
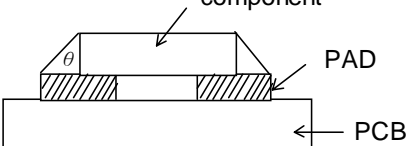
Major defect: AQL = 0.65%

Minor defect: AQL = 1.5%

**7-4. Criteria****1. COB**

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

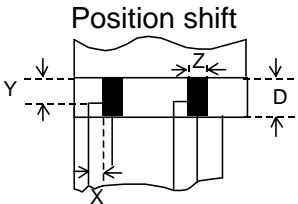
**2. SMT**

Defect	Inspection Item	Inspection Standards	
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation)		Reject
Minor	Component position shift 	$X < 3/4Z$ $Y > 1/3D$	Reject Reject
Minor	Component tilt 	$Y > 1/3D$	Reject
Minor	Insufficient solder 	$\theta \leq 20^\circ$	Reject

**3. Metal (Plastic) Frame**

Defect	Inspection Item	Inspection Standards		
Major	Crack / breakage	Anywhere		
			Reject	
Minor	Frame Scratch	W	L	Acceptable of Scratch
		$w < 0.1\text{mm}$	Any	Ignore
		$0.1 \leq w < 0.2\text{mm}$	$L \leq 5.0\text{mm}$	2
		$0.2 \leq w < 0.3\text{mm}$	$L \leq 3.0\text{mm}$	1
		$w \geq 0.3\text{mm}$	Any	0
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored .		
Minor	Frame Dent , Prick $\Phi = \frac{L + W}{2}$		Acceptable of Dents / Pricks	
		$\Phi \leq 1.0\text{mm}$	2	
		$1.0 < \Phi \leq 1.5\text{mm}$	1	
		$1.5\text{mm} < \Phi$	0	
Note : 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored				
Minor	Frame Deformation	Exceed the dimension of drawing		
Minor	Metal Frame Oxidation	Any rust		

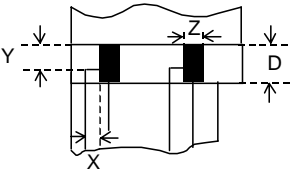
**4. Flexible Film Connector (FFC)**

Defect	Inspection Item	Inspection Standards	
Minor	Tilted soldering	Within the angle $+5^\circ$	Acceptable
Minor	Uneven solder joint /bump		Reject
Minor	Hole $\Phi = \frac{L + W}{2}$	Expose the conductive line	Reject
		$\Phi > 1.0\text{mm}$	Reject
Minor		$Y > 1/3D$	Reject
		$X > 1/2Z$	Reject

**5. Screw**

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

**6. Heatseal 、TCP 、FPC**

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L+W}{2}$	$\Phi > 0.5\text{mm}$	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift 	$Y > 1/3D$	Reject
		$X > 1/2Z$	Reject
Major	Conductive line break		Reject

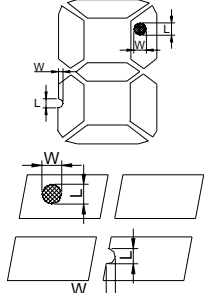
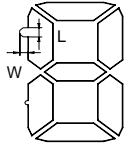
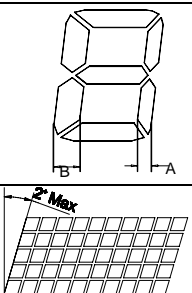
**7. LED Backing Protective Film and Others**

Defect	Inspection Item	Inspection Standards	
Minor	LED dirty, prick	Acceptable number of units	
		$\Phi \leq 0.10\text{mm}$	Ignore
		$0.10 < \Phi \leq 0.15\text{mm}$	2
		$0.15 < \Phi \leq 0.2\text{mm}$	1
		$\Phi > 0.2\text{mm}$	0
		The distance between any two spots should be $\geq 5\text{mm}$ Any spot/dot/void outside of viewing area is acceptable	
Minor	Protective film tilt	Not fully cover LCD	Reject
Major	COG coating	Not fully cover ITO circuit	Reject

**8. Electric Inspection**

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

## 9. Inspection Specification of LCD

Defect	Inspect Item	Inspection Standards					
Minor	Linear Defect	* Glass Scratch * Polarizer Scratch * Fiber and Linear material	W	$W \leq 0.03$	$0.03 < W \leq 0.05$	$W > 0.05$	
			L	$L < 5$	$L < 3$	Any	
			ACC. NO.	1	1	Reject	
			Note	L is the length and W is the width of the defect			
Minor	Black Spot and Polarizer Pricked	* Foreign material between glass and polarizer or glass and glass * Polarizer hole or protuberance by external force	$\Phi$	$\Phi \leq 0.1$	$0.1 < \Phi \leq 0.15$	$0.15 < \Phi \leq 0.2$	$\Phi > 0.2$
			ACC. NO.	3EA / 100mm <sup>2</sup>	2	1	0
			Note	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.			
Minor	White Spot and Bubble in polarizer	* Unobvious transparent foreign material between glass and glass or glass and polarizer * Air protuberance between polarizer and glass	$\Phi$	$\Phi \leq 0.3$	$0.3 < \Phi \leq 0.5$	$0.5 < \Phi$	
			ACC. NO.	3EA / 100mm <sup>2</sup>	1	0	
			Note	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.			
Minor	Segment Defect		$\Phi$	$\Phi \leq 0.10$	$0.10 < \Phi \leq 0.20$	$0.20 < \Phi \leq 0.25$	$\Phi > 0.25$
			ACC. NO.	3EA / 100mm <sup>2</sup>	2	1	0
			Note	W is more than 1/2 segment width			Reject
			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm			
Minor	Protuberant Segment	 $\Phi = (L + W) / 2$	$\Phi$	$\Phi \leq 0.10$	$0.10 < \Phi \leq 0.20$	$0.20 < \Phi \leq 0.25$	$\Phi > 0.25$
			W	Glue	$W \leq 1/2$ Seg $W \leq 0.2$	$W \leq 1/2$ Seg $W \leq 0.2$	Ignore
			ACC. NO.	3EA / 100mm <sup>2</sup>	2	1	0
Minor	Assembly Mis-alignment		1. Segment				
			B	$B \leq 0.4\text{mm}$	$0.4 < B \leq 1.0\text{mm}$	$B > 1.0\text{mm}$	
			B-A	$B-A < 1/2B$	$B-A < 0.2$	$B-A < 0.25$	
			Judge	Acceptable	Acceptable	Acceptable	
			2. Dot Matrix				
Deformation > 2°				Reject			
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"				



**8. RELIABILITY**

NO.	Item	Condition	Criterion
1	High Temperature Operating	60°C , 96Hrs	No defect in cosmetic and operational function allowable. Total current Consumption should be below double of initial value.
2	Low Temperature Operating	-10°C , 96Hrs	
3	High Humidity	50°C , 90%RH, 96Hrs	
4	High Temperature Storage	70°C , 96Hrs	
5	Low Temperature Storage	-20°C , 96Hrs	
6	Vibration	Random wave 10 ~ 100Hz Acceleration: 2g 2 Hrs per direction(X,Y,Z)	
7	Thermal Shock	-10°C to 25°C to 60°C (60Min) (5Min) (60Min) 16Cycles	
8	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV  Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

## 9. HANDLING PRECAUTION

### (1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

### (2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifluro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics

### (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

### (4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

### (5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is reequired.

### (6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

### (7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

# 10. OUTLINE DIMENSION

